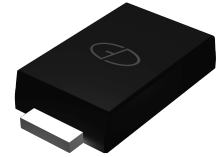


**Features**

- Low reverse current
- Fast reverse recovery time
- Terminals: Plated leads solderable per MIL-STD-750, Method 2026 guaranteed



**SMBF**

**Maximum Ratings** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

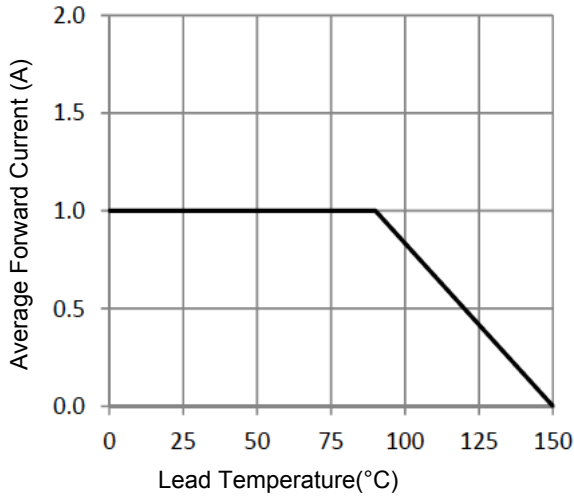
Parameter	Symbol	Value	Unit
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	1200	V
Maximum RMS Voltage	$V_{RMS}$	840	V
Maximum DC Blocking Voltage	$V_{DC}$	1200	V
Maximum Average Forward Rectified Current	$I_F$	1.0	A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	$I_{FSM}$	30	A
Maximum Instantaneous Forward Voltage $I_F=1A@25^\circ\text{C}$	$V_F$	1.9	V
Maximum DC Reverse Current at Rated DC Blocking Voltage@ $T_J=25^\circ\text{C}$	$I_R$	5	$\mu\text{A}$
Maximum DC Reverse Current at Rated DC Blocking Voltage@ $T_J=125^\circ\text{C}$		100	
Typical Junction Capacitance <sup>1</sup>	$C_J$	10.5	pF
Maximum Reverse Recovery Time <sup>2</sup>	$T_{rr}$	75	nS
Typical Thermal Resistance	$R_{\theta JL}$	30	$^\circ\text{C/W}$
Operating Junction Temperature Range	$T_J$	-55 To +150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 To +150	$^\circ\text{C}$

Note:

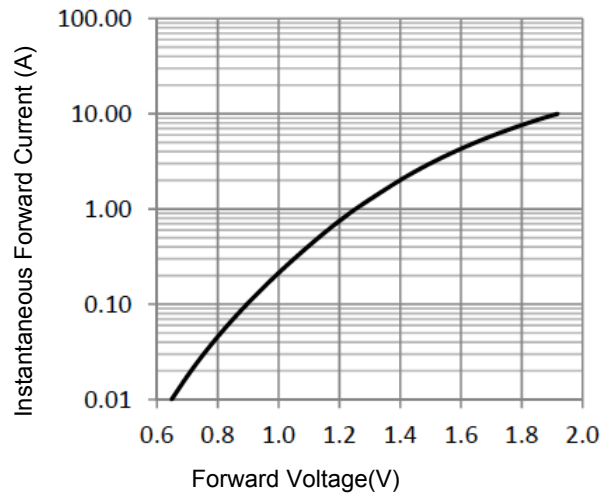
1.Measured at 1.0MHz and applied reverse voltage of 4.0V DC

2:Measured with  $I_F=0.5A$ ,  $I_R=1A$ ,  $I_{RR}=0.25A$

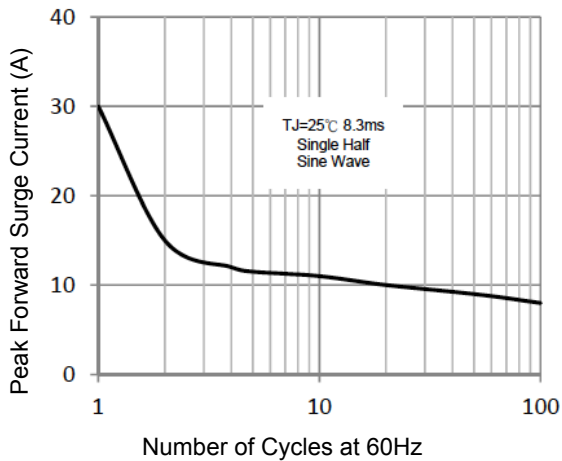
**Ratings and Characteristics Curves** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)



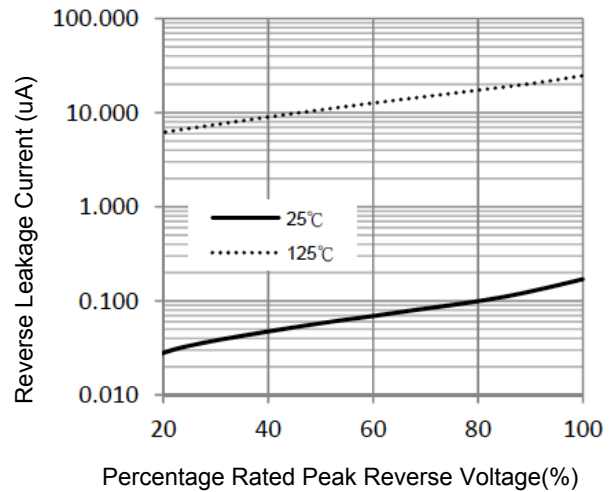
**Figure 1. Typical Forward Current Derating Curve**



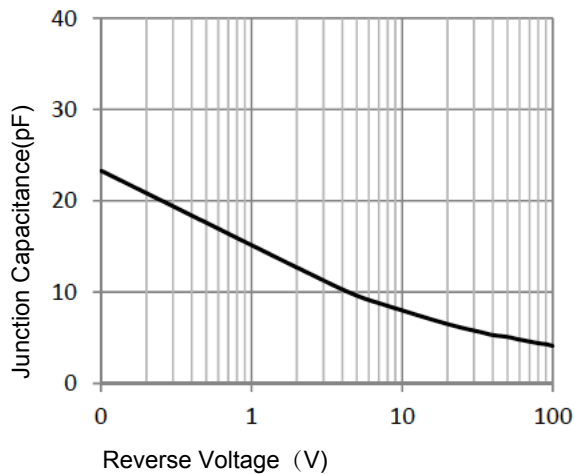
**Figure 2. Typical Forward Characteristics**



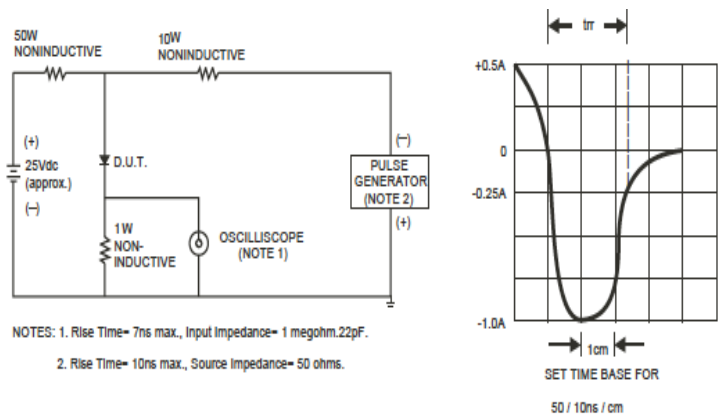
**Figure 3. Maximum Non-Repetitive Forward Surge Current**



**Figure 4. Typical Reverse Characteristics**

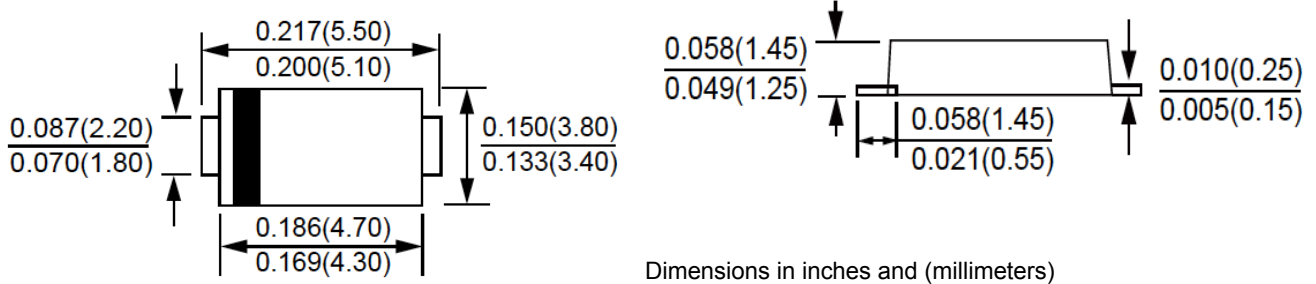


**Figure 5. Typical Junction Capacitance**



**Figure 6. Reverse Recovery Time Characteristic and Test Circuit**

**Package Outline Dimensions SMBF**



**Recommended Pad Layout**

